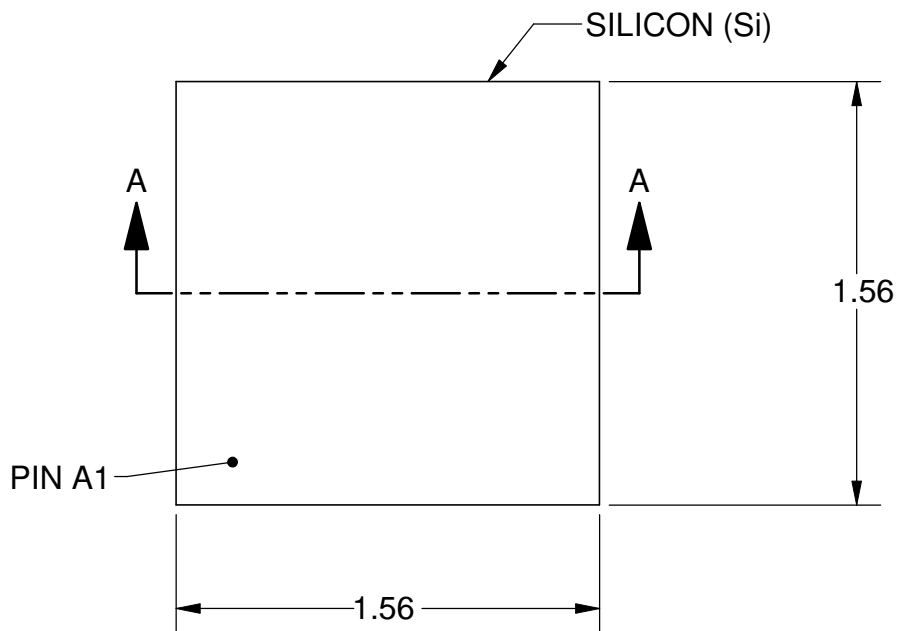
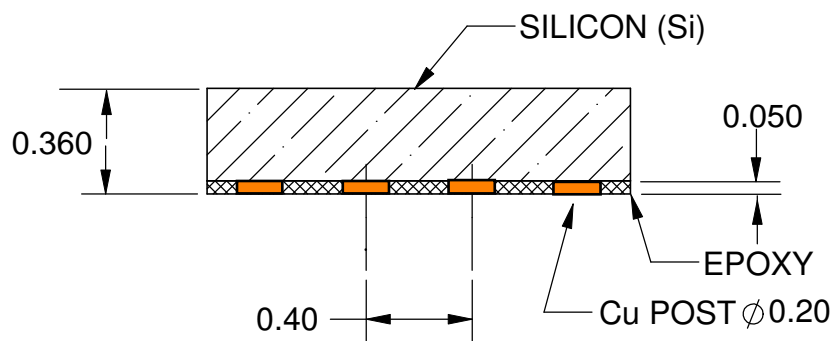
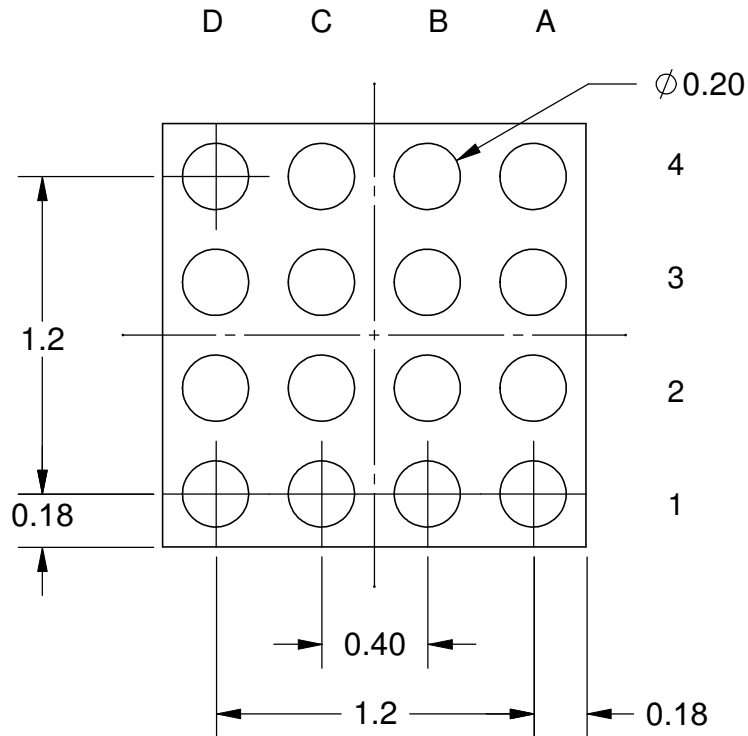


TOP VIEW




PAD VIEW



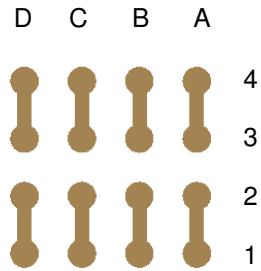
SECTION A-A

- Notes: (Unless Otherwise Specified).
 1) ALL DIMENSIONS ARE IN MM.
 2) PAD ALLOY: Cu (50um Thick)
 3) PAD Cu DIAMETER: 0.20mm..
 4) DIE MATERIAL: Si (SILICON).
 5) DAISY CHAIN PATTERN (SEE PAGE 2).

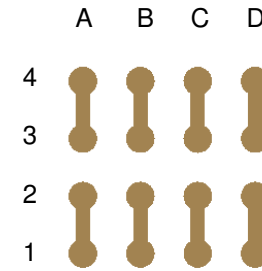
TOLERANCE UNLESS NOTED		APPROVALS	DATE				
X.X	+/- 0.3	DRAWN J. Hines	12/30/2010				TITLE
X.XX	+/- 0.03			eWLP16T.4-DC048D3			
X.XXX	+/- 0.003	ENG		16-L P=0.4mm (TEG0408)			
ANGLES +/- 0.5°		MFG		SCALE	SIZE	DRAWING NO.	REV
ALL DIMENSIONS IN		QA		35:1	A	740480	A
☐ INCHES ☑ MILLIMETERS		CUST		DO NOT SCALE DRAWING			SHEET 1 OF 2
THIRD ANGLE PROJECTION		REVISED					

DAISY CHAIN PATTERN

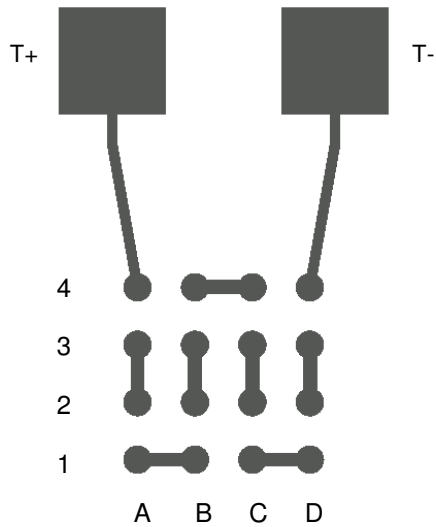
PAD VIEW



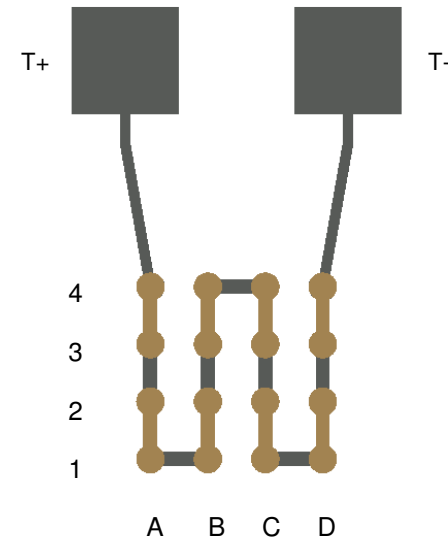
BOTTOM SIDE
(TOP X-RAY VIEW)



TOP VIEW



AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)



TEST VEHICLE BOARD

Notes:

1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE.
DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.

TopLine ®			
TITLE eWLP16T.4C-DC048D3 16-L P=0.4mm (TEG0408)			
SCALE 19:1	SIZE A	DRAWING NO. 740480	REV A
DO NOT SCALE DRAWING		SHEET 2 OF 2	